

Stephane Grauby

List of Publications by Year in descending order

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59
papers

1,049
citations

471061

17
h-index

433756

31
g-index

60
all docs

60
docs citations

60
times ranked

1023
citing authors

#	ARTICLE	IF	CITATIONS
1	Imaging Thermoelectric Properties at the Nanoscale. <i>Nanomaterials</i> , 2021, 11, 1199.	1.9	2
2	Ultimate-resolution thermal spectroscopy in time domain thermoreflectance (TDTR). <i>Journal of Applied Physics</i> , 2020, 128, 065106.	1.1	7
3	Si and Ge allotrope heterostructured nanowires: experimental evaluation of the thermal conductivity reduction. <i>Nanotechnology</i> , 2019, 30, 375704.	1.3	5
4	Thermal Behavior of High Power GaAs-Based Laser Diodes in Vacuum Environment. <i>IEEE Photonics Technology Letters</i> , 2016, 28, 665-668.	1.3	2
5	Precise Facet Temperature Distribution of High- Power Laser Diodes: Unpumped Window Effect. <i>IEEE Photonics Technology Letters</i> , 2015, 27, 1002-1005.	1.3	10
6	Investigations on electro-optical and thermal performances degradation of high power density GaAs-based laser diode in vacuum environment. <i>Microelectronics Reliability</i> , 2015, 55, 1746-1749.	0.9	2
7	Decrease in thermal conductivity in polymeric P3HT nanowires by size-reduction induced by crystal orientation: new approaches towards thermal transport engineering of organic materials. <i>Nanoscale</i> , 2014, 6, 7858-7865.	2.8	63
8	Electro-thermal characterization of a differential temperature sensor in a 65nm CMOS IC: Applications to gain monitoring in RF amplifiers. <i>Microelectronics Journal</i> , 2014, 45, 484-490.	1.1	3
9	Fabrication of Bi ₂ Te ₃ nanowire arrays and thermal conductivity measurement by 3D-scanning thermal microscopy. <i>Journal of Applied Physics</i> , 2013, 113, .	1.1	56
10	Si and SiGe Nanowires: Fabrication Process and Thermal Conductivity Measurement by 3D-Scanning Thermal Microscopy. <i>Journal of Physical Chemistry C</i> , 2013, 117, 9025-9034.	1.5	33
11	Effect of nanostructuring on the thermal conductivity of thermoelectric materials. , 2013, , .		2
12	Nanoscale Block Copolymer Ordering Induced by Visible Interferometric Micropatterning: A Route towards Large Scale Block Copolymer 2D Crystals. <i>Advanced Materials</i> , 2013, 25, 213-217.	11.1	40
13	Scanning thermal microscopy of individual silicon nanowires. <i>Journal of Applied Physics</i> , 2011, 109, .	1.1	78
14	Heterodyne picosecond thermoreflectance applied to nanoscale thermal metrology. <i>Journal of Applied Physics</i> , 2011, 110, .	1.1	48
15	Nonlinearity characterization of temperature sensing systems for integrated circuit testing by intermodulation products monitoring. <i>Review of Scientific Instruments</i> , 2011, 82, 094902.	0.6	0
16	Strategies for built-in characterization testing and performance monitoring of analog RF circuits with temperature measurements. <i>Measurement Science and Technology</i> , 2010, 21, 075104.	1.4	26
17	Thermal exchange radius measurement: Application to nanowire thermal imaging. <i>Review of Scientific Instruments</i> , 2010, 81, 073701.	0.6	63
18	Heterodyne lock-in thermal coupling measurements in integrated circuits: Applications to test and characterization. <i>Review of Scientific Instruments</i> , 2009, 80, 026101.	0.6	3

#	ARTICLE	IF	CITATIONS
19	Investigating Coherent Zone-Folded Acoustic Phonons in Si/SiGe Superlattices by Transient Thermoreflectance Technique. Materials Research Society Symposia Proceedings, 2009, 1221, 8031.	0.1	0
20	Joule expansion imaging techniques on microelectronic devices. Microelectronics Journal, 2009, 40, 1367-1372.	1.1	10
21	Fast Laser Scanning Imaging System for Surface Displacement Measurements. IEEE Electron Device Letters, 2009, 30, 222-224.	2.2	1
22	Nanoscale Thermal Transport Studied With Heterodyne Picosecond Thermoreflectance. , 2009, , .		3
23	Comparison of thermoreflectance and scanning thermal microscopy for microelectronic device temperature variation imaging: Calibration and resolution issues. Microelectronics Reliability, 2008, 48, 204-211.	0.9	15
24	Laser scanning thermomechanical imaging of microelectronic devices. , 2008, , .		1
25	Using Temperature as Observable of the Frequency Response of RF CMOS Amplifiers. , 2008, , .		2
26	A heterodyne method for the thermal observation of the electrical behavior of high-frequency integrated circuits. Measurement Science and Technology, 2008, 19, 115704.	1.4	16
27	Cross-plan Si ¹⁰⁰ /SiGe superlattice acoustic and thermal properties measurement by picosecond ultrasonics. Journal of Applied Physics, 2007, 101, 013705.	1.1	20
28	Coherent phonons in Si ¹⁰⁰ /SiGe superlattices. Physical Review B, 2007, 75, .	1.1	58
29	Laser scanning thermoreflectance imaging system using galvanometric mirrors for temperature measurements of microelectronic devices. Review of Scientific Instruments, 2007, 78, 074902.	0.6	15
30	Joule expansion imaging techniques on microelectronic devices. , 2007, , .		1
31	Dynamical behavior and cut-off frequency of Si/SiGe microcoolers. Superlattices and Microstructures, 2007, 41, 7-16.	1.4	15
32	Harmonic Regime Analysis and Inverse Method Applied to The Simultaneous Determination of Thermoelectric Properties. , 2006, , .		4
33	Time gating imaging through thick silicon substrate: a new step towards backside characterisation. Microelectronics Reliability, 2006, 46, 1520-1524.	0.9	10
34	ElectroStatic Discharge Fault Localization by Laser Probing. Microelectronics Reliability, 2005, 45, 1482-1486.	0.9	2
35	Dynamical behavior of the scanning thermal microscope (SThM) thermal resistive probe studied using Si/SiGe microcoolers. Superlattices and Microstructures, 2005, 38, 69-75.	1.4	10
36	Study of thermomechanical properties of Si ¹⁰⁰ /SiGe superlattices using femtosecond transient thermoreflectance technique. Applied Physics Letters, 2005, 87, 103506.	1.5	16

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37	Simulation of Si/SiGe micro-cooler by thermal quadrupoles method. , 2005, , .		1
38	Temperature variation mapping of a microelectromechanical system by thermoreflectance imaging. IEEE Electron Device Letters, 2005, 26, 78-80.	2.2	15
39	Thermoreflectance calibration procedure on a laser diode: application to catastrophic optical facet damage analysis. IEEE Electron Device Letters, 2005, 26, 461-463.	2.2	24
40	Characterization of thermoelectric devices by laser induced Seebeck electromotive force (LIS-EMF) measurement. Journal Physics D: Applied Physics, 2005, 38, 1489-1497.	1.3	2
41	Calibration procedure for temperature measurements by thermoreflectance under high magnification conditions. Applied Physics Letters, 2004, 84, 822-824.	1.5	62
42	Strain Energy Imaging of a Power MOS Transistor Using Speckle Interferometry. IEEE Transactions on Reliability, 2004, 53, 293-296.	3.5	0
43	Thermal study of PN thermoelectric couple by laser induced Seebeck EMF measurement. Superlattices and Microstructures, 2004, 35, 375-387.	1.4	2
44	Applications of temperature phase measurements to IC testing. Microelectronics Reliability, 2004, 44, 95-103.	0.9	7
45	Thermal parameters identification of micrometric layers of microelectronic devices by thermoreflectance microscopy. Microelectronics Journal, 2004, 35, 811-816.	1.1	20
46	Characterization of the thermal behavior of PN thermoelectric couples by scanning thermal microscope. Microelectronics Journal, 2004, 35, 797-803.	1.1	21
47	Application of Picosecond Ultrasonics to Non-Destructive Analysis in VLSI circuits. Microelectronics Reliability, 2003, 43, 1803-1807.	0.9	1
48	Laser Seebeck Effect Imaging (SEI) and Peltier Effect Imaging (PEI): complementary investigation methods.. Microelectronics Reliability, 2003, 43, 1609-1613.	0.9	8
49	Measurement of thermally induced vibrations of microelectronic devices by use of a heterodyne electronic speckle pattern interferometry imaging technique. Applied Optics, 2003, 42, 1763.	2.1	2
50	Imaging setup for temperature, topography, and surface displacement measurements of microelectronic devices. Review of Scientific Instruments, 2003, 74, 645-647.	0.6	23
51	Surface displacement imaging by interferometry with a light emitting diode. Applied Optics, 2002, 41, 4996.	2.1	14
52	Four different approaches for the measurement of IC surface temperature: application to thermal testing. Microelectronics Journal, 2002, 33, 689-696.	1.1	41
53	Laser diode COFD analysis by thermoreflectance microscopy. Microelectronics Reliability, 2001, 41, 1597-1601.	0.9	13
54	High resolution photothermal imaging of high frequency phenomena using a visible charge coupled device camera associated with a multichannel lock-in scheme. Review of Scientific Instruments, 1999, 70, 3603-3608.	0.6	128

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55	2 MHz modulated photothermal imaging using a CCD camera coupled to a multichannel lock-in detection. , 1999, , .		1
56	High resolution AC temperature field imaging. Electronics Letters, 1997, 33, 1688.	0.5	13
57	Study of the thermal behaviour of PN thermoelectric couples by laser probe interferometric measurement. , 0, , .		1
58	Determination of ZT of PN thermoelectric couples by AC electrical measurement. , 0, , .		3
59	Thermal and thermomechanical study of micro-refrigerators on a chip based on semiconductor heterostructures. , 0, , .		1